

# PS2861B-1

R08DS0100EJ0302

Rev.3.02

4-PIN SSOP PHOTOCOUPLER OPERATING AMBIENT TEMPERATURE 110°C

Feb 25, 2020

## DESCRIPTION

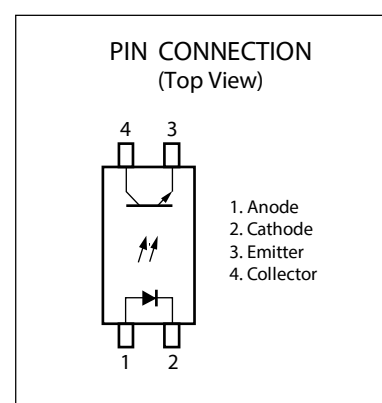
The PS2861B-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

The package has a shield effect to cut off ambient light, and is mounted in a Shrink SOP (Small Outline Package) for high density applications.

Due to the high isolation voltage between the input and output, the PS2861B-1 is suitable for interface and signal transfer circuits that require surface or high-density mounting.

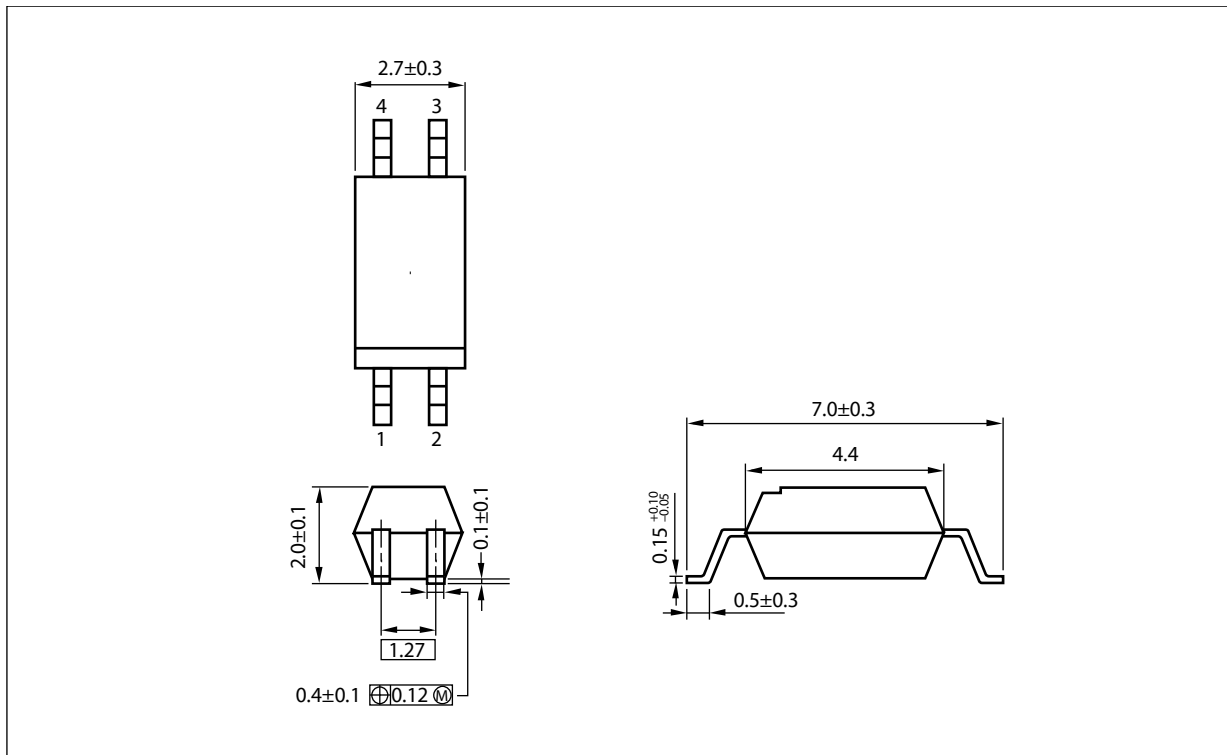
## FEATURES

- Operating ambient temperature: 110°C
- Isolation distance (0.4 mm MIN.)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- Shrink SOP (Small Outline Package) type
- High-speed switching ( $t_r = 4\mu s$  TYP.,  $t_f = 5\mu s$  TYP.)
- Embossed tape product: PS2861B-1-F3: 3 500 pcs/reel
- Pb-Free product
- Safety standards
  - UL approved: UL1577, Single protection
  - CSA approved: CAN/CSA-C22.2 No. 62368-1, Reinforced insulation
  - BSI approved: BS EN 62368-1, Reinforced insulation
  - SEMKO approved: EN 62368-1, IEC 62368-1, Reinforced insulation
  - NEMKO approved: EN 62368-1, Reinforced insulation
  - FIMKO approved: EN 62368-1, Reinforced insulation
  - DEMKO approved: EN 62368-1, Reinforced insulation
  - CQC approved: GB8898, GB4943.1, Reinforced insulation
  - VDE approved: DIN EN 60747-5-5 (Option)



## APPLICATIONS

- Power supply
- Programmable logic controllers

**PACKAGE DIMENSIONS (UNIT: mm)**

Weight ( 4-pin SSOP) : 0.05 g (typ.)

**PHOTOCOUPLER CONSTRUCTION**

| Parameter          | Unit (MIN.) |
|--------------------|-------------|
| Air Distance       | 5.0 mm      |
| Creepage Distance  | 5.0 mm      |
| Isolation Distance | 0.4 mm      |

MARKING EXAMPLE

|                                |                                                                                                                                                                                                                                             |
|--------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Made in Taiwan                 | <div><div>Company initial</div><div><div>R1B</div><div>301</div></div><div><div>Last 2 numbers of type<br/>No. : 1B</div><div>Assembly Lot<br/>301</div><div>Week Assembled<br/>1</div><div>Year Assembled (Last 1 digit)</div></div></div> |
| Made in Taiwan<br>Halogen free | <div><div>R1B</div><div>301</div></div> <div>" " (Vertical bar)<br/>:Made in Taiwan &amp; Halogen free</div>                                                                                                                                |
| Made in Japan                  | <div><div>R1B</div><div>□301</div></div> <div>"□" (Square)<br/>:Made in Japan</div>                                                                                                                                                         |
| Made in Japan<br>Halogen free  | <div><div>R1B</div><div>—301</div></div> <div>"—" (Horizontal bar)<br/>:Made in Japan &amp; Halogen free</div>                                                                                                                              |

## ORDERING INFORMATION

| Part Number    | Order Number      | Solder Plating Specification | Packing Style                   | Safety Standard Approval                                                                | Application Part Number*1 |
|----------------|-------------------|------------------------------|---------------------------------|-----------------------------------------------------------------------------------------|---------------------------|
| PS2861B-1      | PS2861B-1Y-A      | Pb-Free and Halogen Free     | 50 pcs<br>(Tape 50 pcs cut)     | Standard products<br>(UL, CSA, BSI,<br>SEMKO, NEMKO,<br>FIMKO, DEMKO,<br>CQC approved)  | PS2861B-1                 |
| PS2861B-1-F3   | PS2861B-1Y-F3-A   |                              | Embossed Tape<br>3 500 pcs/reel |                                                                                         |                           |
| PS2861B-1-V    | PS2861B-1Y-V-A    |                              | 50 pcs<br>(Tape 50 pcs cut)     | UL, CSA, BSI,<br>SEMKO, NEMKO,<br>FIMKO, DEMKO,<br>CQC,<br>DIN EN 60747-5-5<br>approved |                           |
| PS2861B-1-V-F3 | PS2861B-1Y-V-F3-A |                              | Embossed Tape<br>3 500 pcs/reel |                                                                                         |                           |

Note: \*1. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

| Parameter                     |                              | Symbol                      | Ratings     | Unit                 |
|-------------------------------|------------------------------|-----------------------------|-------------|----------------------|
| Diode                         | Forward Current (DC)         | $I_F$                       | 50          | mA                   |
|                               | Reverse Voltage              | $V_R$                       | 6           | V                    |
|                               | Power Dissipation Derating   | $\Delta P_D/^\circ\text{C}$ | 0.6         | mW/ $^\circ\text{C}$ |
|                               | Power Dissipation            | $P_D$                       | 60          | mW                   |
|                               | Peak Forward Current*1       | $I_{FP1}$                   | 2.5         | A                    |
|                               | Peak Forward Current*2       | $I_{FP2}$                   | 1.0         |                      |
| Transistor                    | Collector to Emitter Voltage | $V_{CEO}$                   | 70          | V                    |
|                               | Emitter to Collector Voltage | $V_{ECO}$                   | 5           | V                    |
|                               | Collector Current            | $I_C$                       | 50          | mA                   |
|                               | Power Dissipation Derating   | $\Delta P_C/^\circ\text{C}$ | 1.2         | mW/ $^\circ\text{C}$ |
|                               | Power Dissipation            | $P_C$                       | 120         | mW                   |
| Isolation Voltage*3           |                              | BV                          | 3 750       | Vr.m.s.              |
| Operating Ambient Temperature |                              | $T_A$                       | -55 to +110 | $^\circ\text{C}$     |
| Storage Temperature           |                              | $T_{stg}$                   | -55 to +150 | $^\circ\text{C}$     |

Notes: \*1. PW = 10  $\mu\text{s}$ , Duty Cycle = 1%

\*2. PW = 100  $\mu\text{s}$ , Duty Cycle = 1%

\*3. AC voltage for 1 minute at  $T_A = 25^\circ\text{C}$ , RH = 60% between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

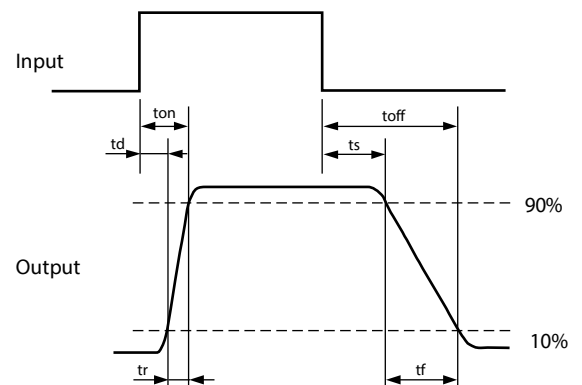
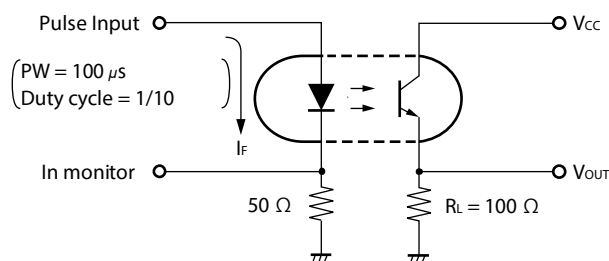
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

|            | Parameter                                                  | Symbol               | Conditions                                                           | MIN.             | TYP. | MAX. | Unit |
|------------|------------------------------------------------------------|----------------------|----------------------------------------------------------------------|------------------|------|------|------|
| Diode      | Forward Voltage                                            | V <sub>F</sub>       | I <sub>F</sub> = 5 mA                                                |                  | 1.1  | 1.4  | V    |
|            | Reverse Current                                            | I <sub>R</sub>       | V <sub>R</sub> = 5 V                                                 |                  |      | 5    | μA   |
|            | Terminal Capacitance                                       | C <sub>t</sub>       | V = 0 V, f = 1 MHz                                                   |                  | 15   |      | pF   |
| Transistor | Collector to Emitter Dark Current                          | I <sub>CEO</sub>     | I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 24 V                        |                  |      | 100  | nA   |
| Coupled    | Current Transfer Ratio (I <sub>C</sub> /I <sub>F</sub> )*1 | CTR                  | I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V                         | 50               | 150  | 300  | %    |
|            |                                                            |                      | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V                         | 10               | 50   |      |      |
|            | Collector Saturation Voltage                               | V <sub>CE(sat)</sub> | I <sub>F</sub> = 10 mA, I <sub>C</sub> = 2 mA                        |                  |      | 0.3  | V    |
|            | Isolation Resistance                                       | R <sub>I-O</sub>     | V <sub>I-O</sub> = 1 kV <sub>DC</sub>                                | 10 <sup>11</sup> |      |      | Ω    |
|            | Isolation Capacitance                                      | C <sub>I-O</sub>     | V = 0 V, f = 1 MHz                                                   |                  | 0.4  |      | pF   |
|            | Rise Time*2                                                | t <sub>r</sub>       | V <sub>CC</sub> = 5 V, I <sub>C</sub> = 2 mA, R <sub>L</sub> = 100 Ω |                  | 4    |      | μs   |
|            | Fall Time*2                                                | t <sub>f</sub>       |                                                                      |                  | 5    |      |      |
|            | Turn-on Time*2                                             | t <sub>on</sub>      |                                                                      |                  | 5    |      |      |
|            | Turn-off Time*2                                            | t <sub>off</sub>     |                                                                      |                  | 5    |      |      |

Notes: \*1. CTR rank

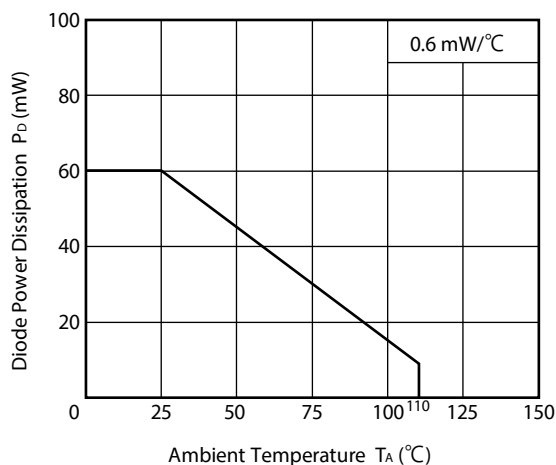
| CTR rank | CTR (%)       | Conditions                                   |
|----------|---------------|----------------------------------------------|
| L        | 100 to 300    | I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V |
|          | 20 and larger | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V |
| M        | 50 to 150     | I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V |
|          | 10 and larger | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V |
| W        | 130 to 260    | I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V |
|          | 26 and larger | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V |
| N        | 50 to 300     | I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V |
|          | 10 and larger | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V |

\*2. Test Circuit for Switching Time

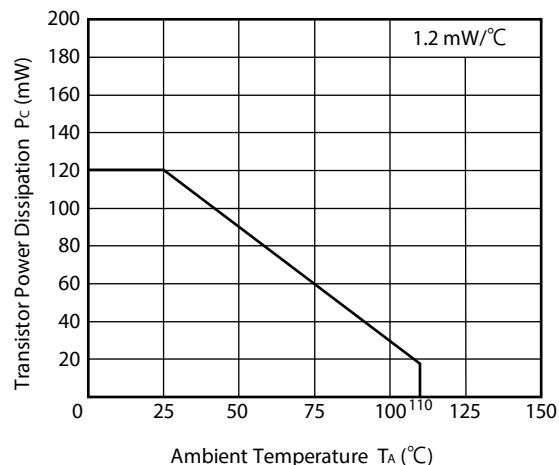


# **TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

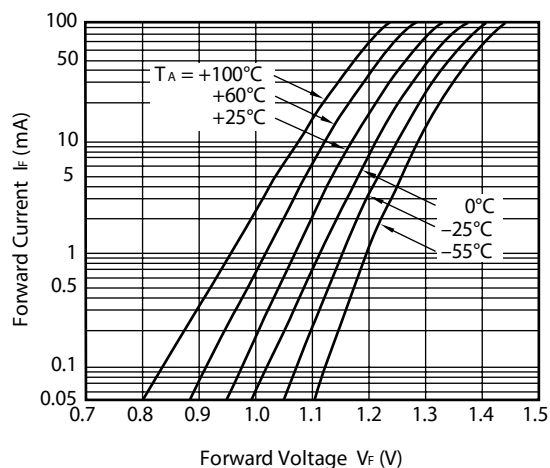
DIODE POWER DISSIPATION vs.  
AMBIENT TEMPERATURE



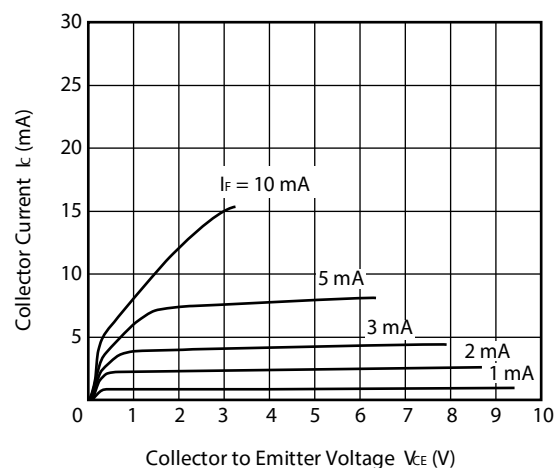
TRANSISTOR POWER DISSIPATION vs.  
AMBIENT TEMPERATURE



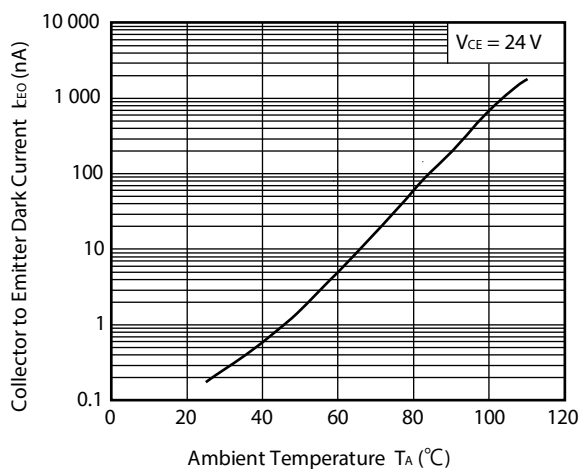
FORWARD CURRENT vs.  
FORWARD VOLTAGE



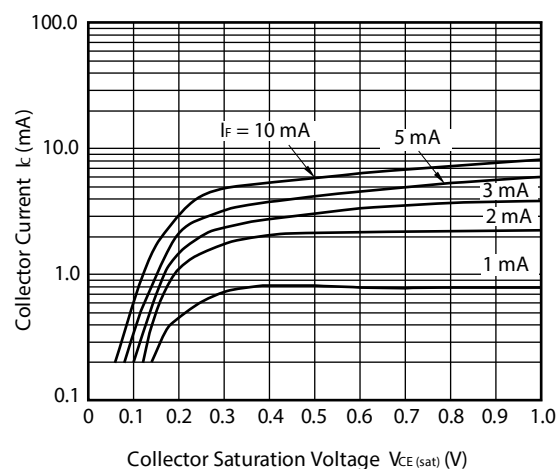
COLLECTOR CURRENT vs.  
COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK  
CURRENT vs. AMBIENT TEMPERATURE

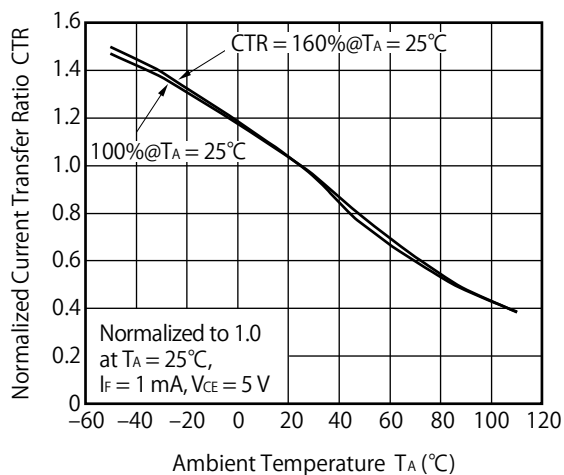


COLLECTOR CURRENT vs.  
COLLECTOR SATURATION VOLTAGE

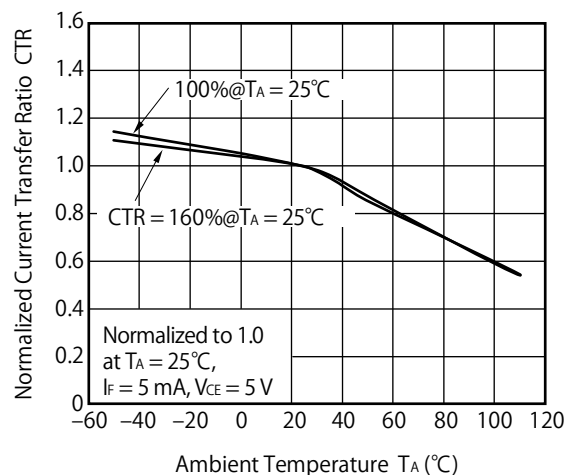


**Remark** The graphs indicate nominal characteristics.

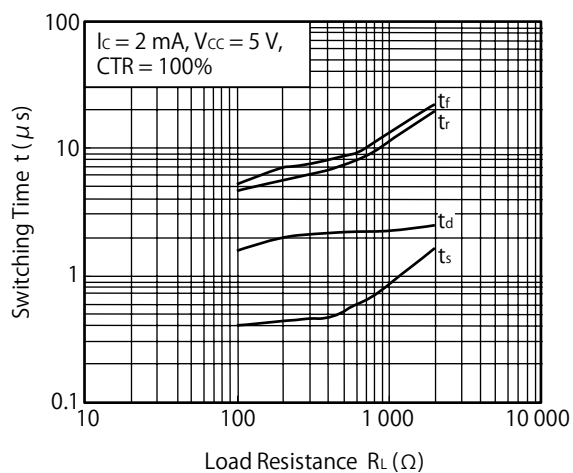
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



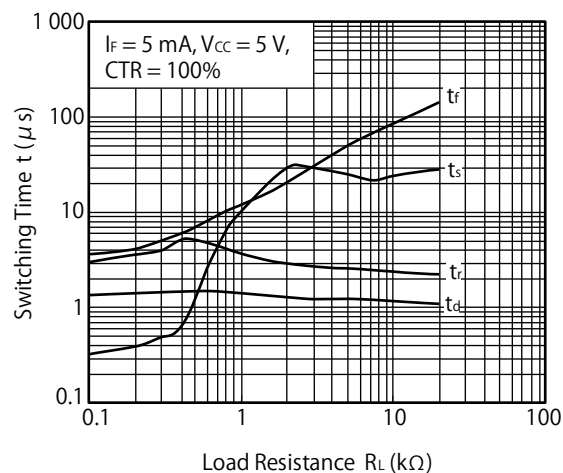
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



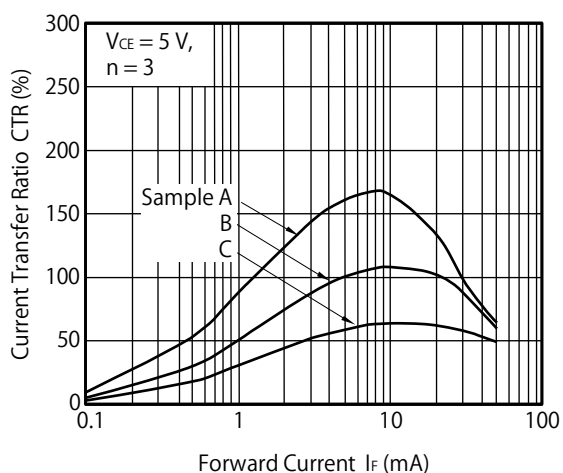
SWITCHING TIME vs. LOAD RESISTANCE



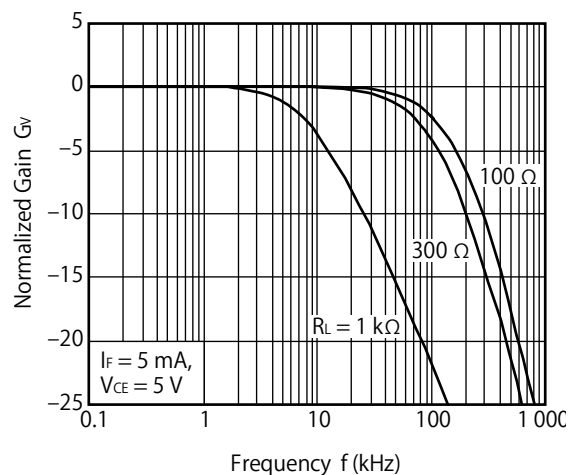
SWITCHING TIME vs. LOAD RESISTANCE



CURRENT TRANSFER RATIO vs. FORWARD CURRENT



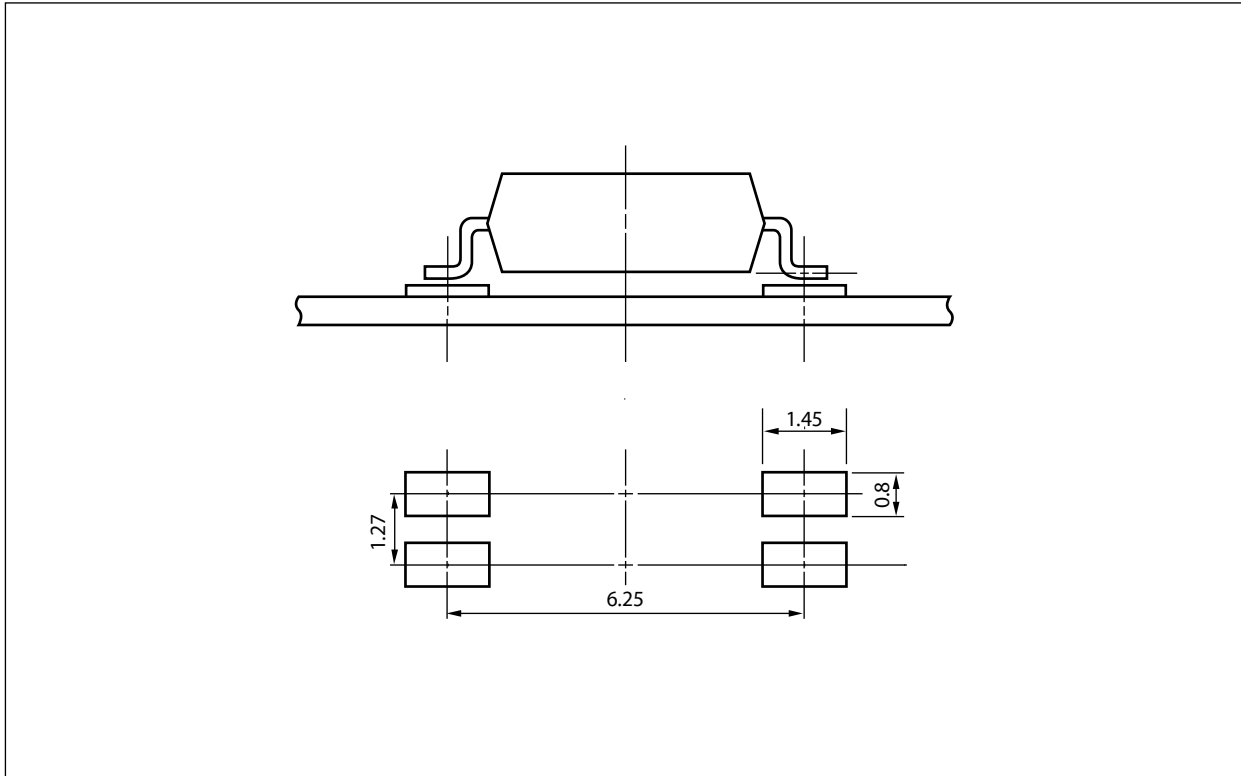
FREQUENCY RESPONSE



**Remark** The graphs indicate nominal characteristics.



## RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** All dimensions in this figure must be evaluated before use.

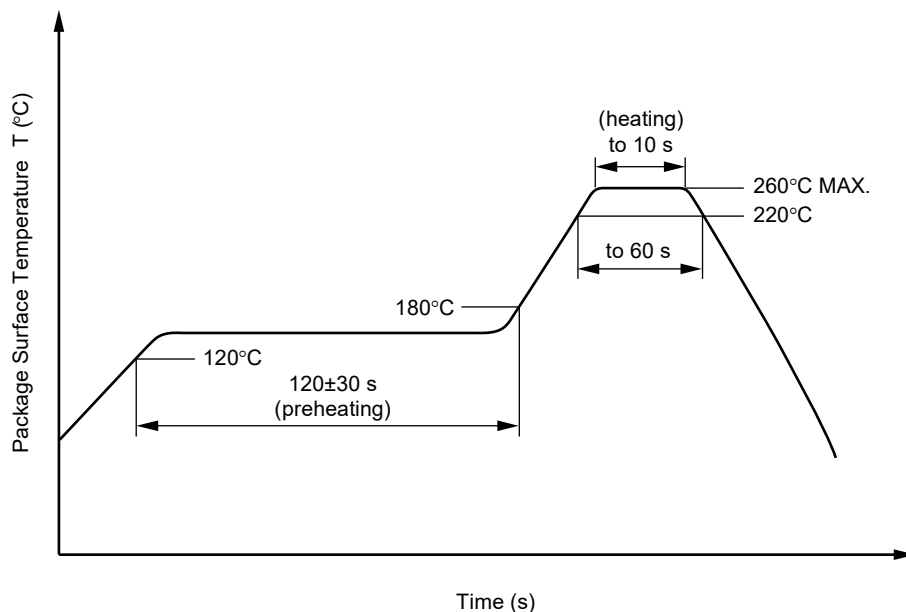
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- |                                                 |                                                                                                                         |
|-------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|
| • Peak reflow temperature                       | 260°C or below (package surface temperature)                                                                            |
| • Time of peak reflow temperature               | 10 seconds or less                                                                                                      |
| • Time of temperature higher than 220°C         | 60 seconds or less                                                                                                      |
| • Time to preheat temperature from 120 to 180°C | 120±30 s                                                                                                                |
| • Number of reflows                             | Three                                                                                                                   |
| • Flux                                          | Rosin flux containing small amount of chlorine<br>(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

- |                         |                                                                                                                      |
|-------------------------|----------------------------------------------------------------------------------------------------------------------|
| • Temperature           | 260°C or below (molten solder temperature)                                                                           |
| • Time                  | 10 seconds or less                                                                                                   |
| • Preheating conditions | 120°C or below (package surface temperature)                                                                         |
| • Number of times       | One (Allowed to be dipped in solder including plastic mold portion.)                                                 |
| • Flux                  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

#### (3) Soldering by Soldering Iron

- |                                            |                                                                                                                         |
|--------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|
| • Peak Temperature (lead part temperature) | 350°C or below                                                                                                          |
| • Time (each pins)                         | 3 seconds or less                                                                                                       |
| • Flux                                     | Rosin flux containing small amount of chlorine<br>(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C

#### (4) Cautions

- Flux Cleaning  
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

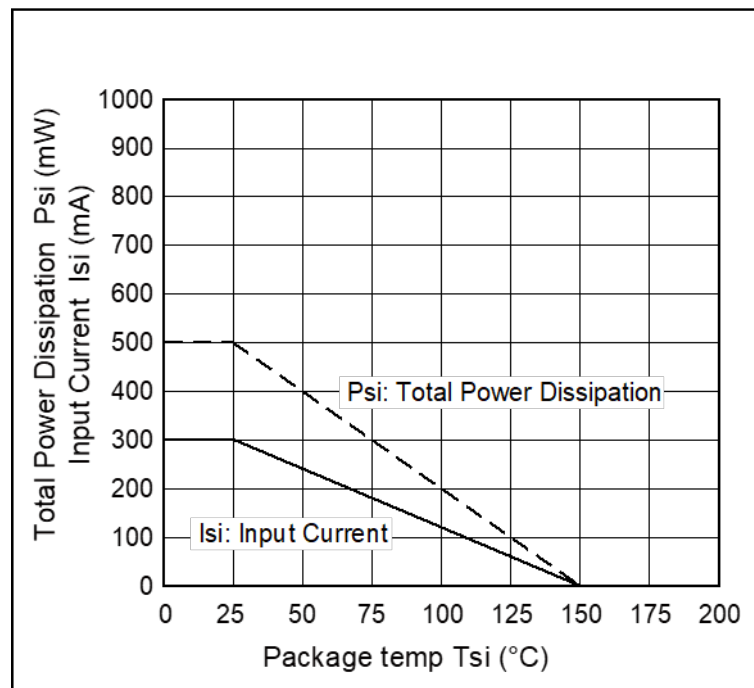
## USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

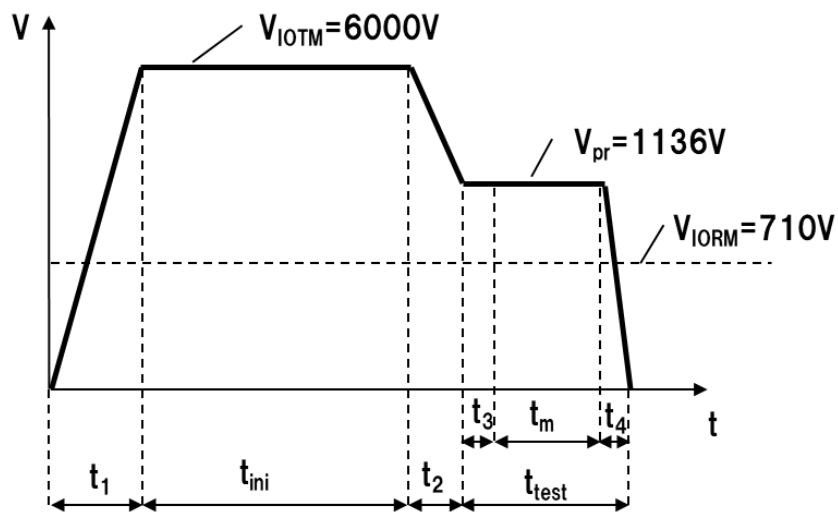
## SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

| Parameter                                                                                                                                                                                                                                                                              | Symbol                                                    | Rating                      | Unit                       |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------|-----------------------------|----------------------------|
| Climatic test class (IEC 60068-1/DIN EN 60068-1)                                                                                                                                                                                                                                       |                                                           | 55/110/21                   |                            |
| Dielectric strength<br>maximum operating isolation voltage<br>Test voltage (partial discharge test, procedure a for type test and random test)<br>$U_{pr} = 1.6 \times U_{IORM}, P_d < 5 \text{ pC}$                                                                                   | $U_{IORM}$<br>$U_{pr}$                                    | 710<br>1 136                | $V_{peak}$<br>$V_{peak}$   |
| Test voltage (partial discharge test, procedure b for all devices)<br>$U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \text{ pC}$                                                                                                                                                             | $U_{pr}$                                                  | 1 331                       | $V_{peak}$                 |
| Highest permissible overvoltage                                                                                                                                                                                                                                                        | $U_{IOTM}$                                                | 6 000                       | $V_{peak}$                 |
| Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))                                                                                                                                                                                                                          |                                                           | 2                           |                            |
| Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))                                                                                                                                                                                                                      | CTI                                                       | 175                         |                            |
| Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))                                                                                                                                                                                                                               |                                                           | III a                       |                            |
| Storage temperature range                                                                                                                                                                                                                                                              | $T_{stg}$                                                 | -55 to +150                 | °C                         |
| Operating temperature range                                                                                                                                                                                                                                                            | $T_A$                                                     | -55 to +110                 | °C                         |
| Isolation resistance, minimum value<br>$V_{IO} = 500 \text{ V dc at } T_A = 25^\circ\text{C}$<br>$V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100^\circ\text{C}$                                                                                                          | $R_{is \text{ MIN.}}$<br>$R_{is \text{ MIN.}}$            | $10^{12}$<br>$10^{11}$      | $\Omega$<br>$\Omega$       |
| Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)<br>Package temperature<br>Current (input current $I_F$ , $\Psi_i = 0$ )<br>Power (output or total power dissipation)<br>Isolation resistance<br>$V_{IO} = 500 \text{ V dc at } T_A = T_{si}$ | $T_{si}$<br>$I_{si}$<br>$\Psi_i$<br>$R_{is \text{ MIN.}}$ | 150<br>300<br>500<br>$10^9$ | °C<br>mA<br>mW<br>$\Omega$ |

## Dependence of maximum safety ratings with package temperature



### Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1$  to  $10$  sec

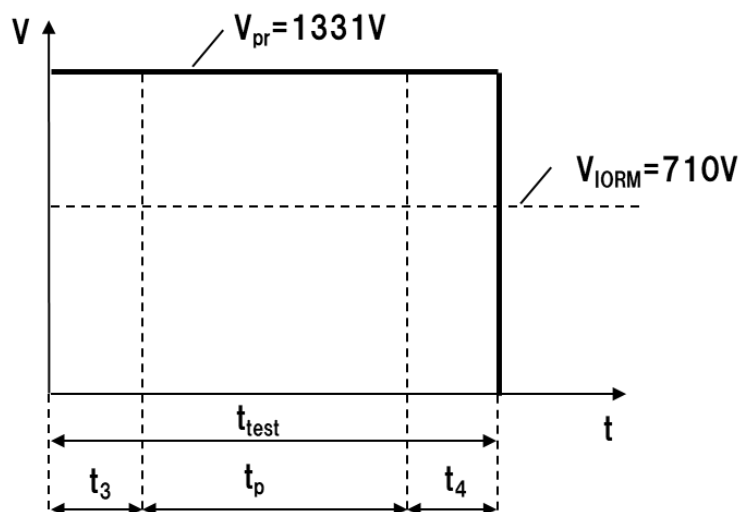
$t_3, t_4 = 1$  sec

$t_m$  (PARTIAL DISCHARGE) =  $10$  sec

$t_{test} = 12$  sec

$t_{ini} = 60$  sec

### Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1$  sec

$t_p$  (PARTIAL DISCHARGE) =  $1.0$  sec

$t_{test} = 1.2$  sec

**Caution**

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
  2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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